

Description

The TOCS-R2 chips are designed for bidirectional 3-omega measurements using Nanotest's TOCS® system. Chips can be purchased as single chips or as wafers. On each wafer there are four different chip types, which will be described in detail on the next pages.

Technical Specification

Wafer

Fabrication technology	Thin film		
Wafer material	Glass, thermal conductivity 1.2 W/(m·K)		
Wafer size	150	mm	
	6	inch	
Wafer thickness	700	μm	
Cell size	12 x 12	mm²	

Sensor

Sensor type	line resistor		
Sensor material	aluminium		
Sensing method	four-terminal sensing		
Sensor thickness	100	nm	
Sensor width	5-15 (depending on chip-type)	μm	
Resistance value	35-45	Ω	
Temperature coefficient of resistance of sensor	(2.8-3.8)·10 ⁻³	1/K	
Passivation	Silicon oxide (100 μm,200 μm or 300 μm depending on wafer).		
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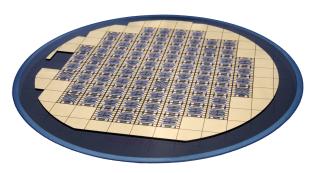


Figure 1 Wafer with TOCS-R2 chips.

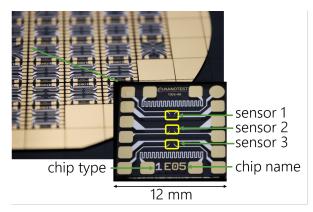


Figure 2 TOCS-R2 chips and chip name.

Chip selection guide

There are 4 different types of chips on the wafer. The chip type is indicated on each chip, as displayed in Figure 2. The location of the chips on the wafer is shown in Figure 3.

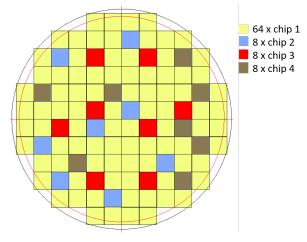


Figure 3 Location of the different chip types on the wafer.

Chip Type 1

This chip type is designed for cross-plane thermal conductivity measurements based on the bidirectional 3-omega method as described, e.g. in Cahill, D. G., *Rev. Sci. Instrum.* **61**, 802-808 (1990), Grosse, C. *et al.*, Sensors and Actuators A **278**, 33-42 (2018), DOI: 10.1016/j.sna.2018.05.030 or Lubner, S. D. *et al.*, *Rev. Sci. Instrum.* **86**, 014905 (2015) or Dames, C., *Annual Review of heat transfer.* 16, 7-49 (2013). It is the main chip type for TOCS. The layout is shown in Figure 4.

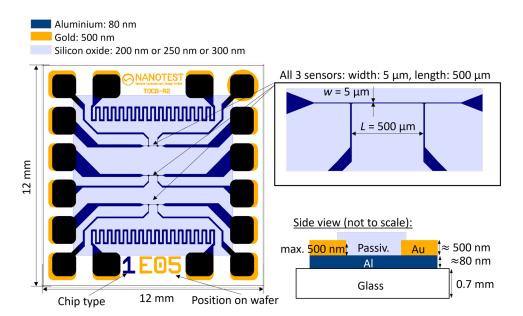


Figure 4 Chip type 1

Application remarks

All offered chips are supposed to be used for characterization purposes. The application of the data from the test die to a functional system lies in the responsibility of the user. Nanotest makes no warranty, express or implied including the implied warranties of merchantability and fitness for a particular purpose, that the user's system designed using that data will perform as intended.